SDAS142C - JULY 1987 - REVISED AUGUST 1995

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- pnp Inputs Reduce dc Loading
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

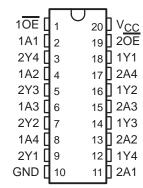
description

These octal buffers and line drivers are designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. With the 'ALS240A, 'ALS241C, 'AS240A, and 'AS241A, these devices provide the choice of selected combinations of inverting outputs, symmetrical active-low output-enable (\overline{OE}) inputs, and complementary \overline{OE} and \overline{OE} inputs.

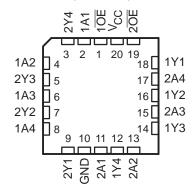
The -1 version of SN74ALS244C is identical to the standard version, except that the recommended maximum I_{OL} for the -1 version is 48 mA. There is no -1 version of the SN54ALS244C.

The SN54ALS244C and SN54AS244A are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS244C and SN74AS244A are characterized for operation from 0°C to 70°C.

SN54ALS244C, SN54AS244A . . . J PACKAGE SN74ALS244C, SN74AS244A . . . DW OR N PACKAGE (TOP VIEW)



SN54ALS244C, SN54AS244A . . . FK PACKAGE (TOP VIEW)



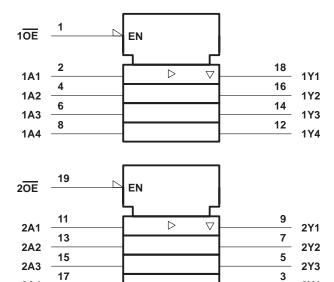
FUNCTION TABLE (each buffer)

INP	JTS	OUTPUT
ŌĒ	Α	Υ
L	Н	Н
L	L	L
Н	Χ	Z

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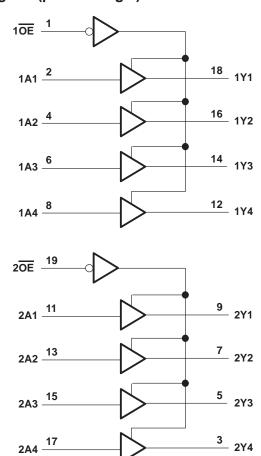
logic symbol[†]

2A4



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

2Y4

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A : SN54ALS244C	−55°C to 125°C
SN74ALS244C	0°C to 70°C
Storage temperature range	-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



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recommended operating conditions

		SNS	54ALS24	4C	SN74ALS244C			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage	2			2			V	
\/	Low-level input voltage			0.8†			0.8	V	
VIL	Low-level input voitage			0.7‡					
ІОН	High-level output current			-12			-15	mA	
lo.	Low lovel output ourropt			12			24	mA	
lOL	Low-level output current						48§	IIIA	
TA	Operating free-air temperature	-55		125	0		70	°C	

[†] Applies over temperature range –55°C to 70°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST (TEST CONDITIONS			4C	SN74ALS244C			UNIT	
PARAMETER	1531 (MAX	MIN	TYP¶	MAX	UNIT	
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V	
	V _{CC} = 4.5 V to 5.5 V	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		VCC -2	<u>)</u>			
Vari	VCC = 4.5 V to 5.5 V	$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V	
VOH	V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2						v	
	vCC = 4.5 v	$I_{OH} = -15 \text{ mA}$				2				
		I _{OL} = 12 mA		0.25	0.4		0.25	0.4		
VOL	V _{CC} = 4.5 V	I _{OL} = 24 mA					0.35	0.5	V	
		I _{OL} = 48 mA (-1 version)					0.35	0.5		
lozh	$V_{CC} = 5.5 \text{ V},$	V _O = 2.7 V			20			20	μΑ	
lozL	$V_{CC} = 5.5 \text{ V},$	V _O = 0.4 V			-20			-20	μΑ	
lj	$V_{CC} = 5.5 V,$	$V_I = 7 V$			0.1			0.1	mA	
lіН	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ	
I _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA	
IO [#]	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA	
		Outputs high		9	18		9	17		
ICC	V _{CC} = 5.5 V	Outputs low		15	25		15	24	mA	
		Outputs disabled	sabled 17 29		17	27				

[¶] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] Applies over temperature range 70°C to 125°C

[§] Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V

[#] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _l R1 R2	_ = 50 pF l = 500 Ω 2 = 500 Ω	2,	,	UNIT
			SN54ALS244C		SN74ALS244C		
			MIN	MAX	MIN	MAX	
t _{PLH}	А		1	16	2	10	ns
t _{PHL}	A	Y	3	12	3	10	113
^t PZH	ŌĒ	V	1	26	3	20	ns
t _{PZL}	OE	Y	1	24	3	20	115
^t PHZ	ŌĒ	Y	2	10	2	10	ns
t _{PLZ}	OL .	'	1	26	1	13	113

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A : SN54AS244A	−55°C to 125°C
SN74AS244A	0°C to 70°C
Storage temperature range	-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54AS244A			SN	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
ІОН	High-level output current			-12			-15	mA
loL	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	0		70	°C

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST O	TEST CONDITIONS		54AS24	4A	SN	LINUT			
PARAMETER	IESI C	ONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT	
VIK	V _{CC} = 4.5 V,	I _I = -18 mA			-1.2			-1.2	V	
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2				
Va		$I_{OH} = -3 \text{ mA}$	2.4	3.4		2.4	3.4		V	
VOH	V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2.4						V	
		$I_{OH} = -15 \text{ mA}$				2.4				
Va	V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55				V	
VOL	VCC = 4.5 V	I _{OL} = 64 mA						0.55	V	
lozh	$V_{CC} = 5.5 V,$	V _O = 2.7 V			50			50	μΑ	
lozL	$V_{CC} = 5.5 V,$	V _O = 0.4 V			-50			-50	μΑ	
Ц	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1			0.1	mA	
lін	$V_{CC} = 5.5 V,$	V _I = 2.7 V			20			20	μΑ	
OE OE	V00 - 5 5 V	V _I = 0.4 V			-0.5			-0.5	mA	
IIL A	V _{CC} = 5.5 V,	V = 0.4 V		-1				-1	ША	
10 [‡]	$V_{CC} = 5.5 V,$	V _O = 2.25 V	-50		-150	-50		-150	mA	
		Outputs high		22	34		22	34		
Icc	V _{CC} = 5.5 V	Outputs low		60	90		60	90	mA	
		Outputs disabled		34	54		34	54		

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	(INPUT) (OUTPUT)		$\begin{array}{c} \text{V}_{\text{CC}} = 4.5 \text{ V to } 5.5 \text{ V,} \\ \text{C}_{\text{L}} = 50 \text{ pF,} \\ \text{R1} = 500 \ \Omega, \\ \text{R2} = 500 \ \Omega, \\ \text{T}_{\text{A}} = \text{MIN to MAX\$} \\ \\ \text{SN54AS244A} \text{SN74AS244A} \\ \end{array}$				
			MIN	MAX	MIN	MAX		
^t PLH	А	V	2	9	2	6.2	ns	
^t PHL	A	Υ	1	7	1	6.2	115	
^t PZH	ŌĒ	V	1	10	1	9	ns	
t _{PZL}	OE	Y	2	8	2	7.5	115	
^t PHZ	ŌĒ	Y	1	6.5	1	6	ns	
t _{PLZ}	OE .	ſ	1	10.5	1	9	115	

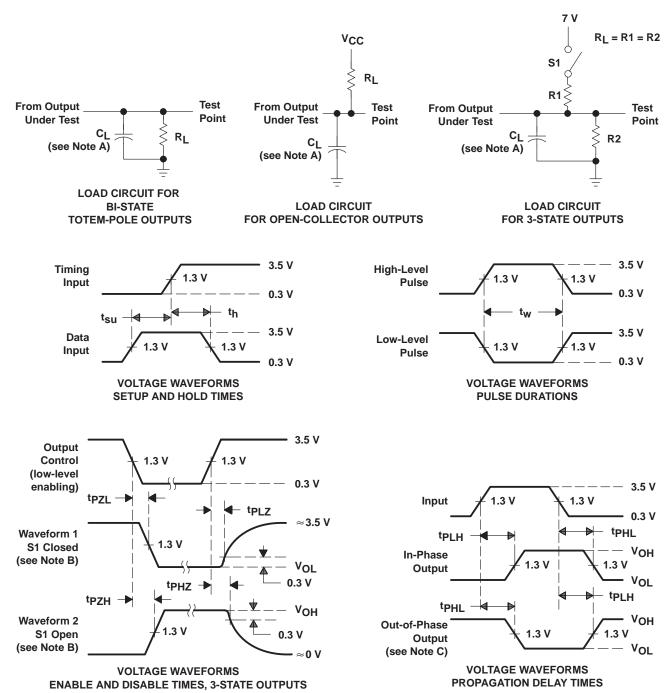
[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGE OPTION ADDENDUM

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-86839012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8683901RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
5962-8683901SA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
5962-8683901VRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
5962-8683901VSA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
5962-9755901Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9755901QRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
5962-9755901QSA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
JM38510/38303B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/38303BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
SN54ALS244CJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
SN54AS244AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
SN74ALS244C-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244C-1DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244C-1DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244C-1DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244C-1DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244C-1DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244C-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS244C-1NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS244C-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244C-1NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244C-1NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244CDBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74ALS244CDBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244CDBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244CDBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244CDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244CDWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244CDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM



PACKAGE OPTION ADDENDUM

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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ALS244CDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244CDWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244CDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244CN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS244CNE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS244CNSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244CNSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS244CNSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS244ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS244ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS244ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS244ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS244ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS244ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS244AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS244ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS244ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS244ANSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS244ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ALS244CFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ALS244CJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
SNJ54ALS244CW	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SNJ54AS244AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54AS244AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
SNJ54AS244AW	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type

 $^{^{(1)}}$ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.



PACKAGE OPTION ADDENDUM

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(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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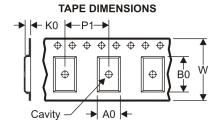




JMENTS
ti.com 5-Aug-2008

TAPE AND REEL INFORMATION





	Α0	Dimension designed to accommodate the component width
	B0	Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
Г	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS244C-1DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS244C-1NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74ALS244CDBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ALS244CDWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS244CNSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74AS244ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74AS244ANSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION





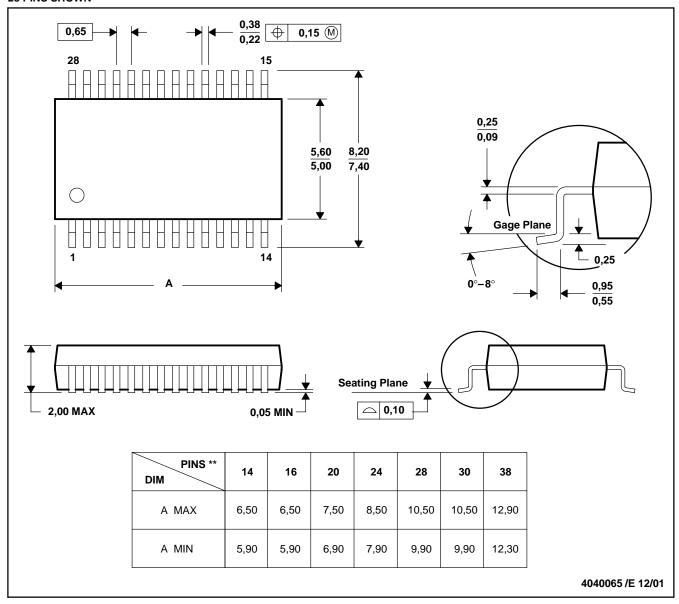
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS244C-1DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74ALS244C-1NSR	SO	NS	20	2000	346.0	346.0	41.0
SN74ALS244CDBR	SSOP	DB	20	2000	346.0	346.0	33.0
SN74ALS244CDWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74ALS244CNSR	SO	NS	20	2000	346.0	346.0	41.0
SN74AS244ADWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74AS244ANSR	SO	NS	20	2000	346.0	346.0	41.0

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

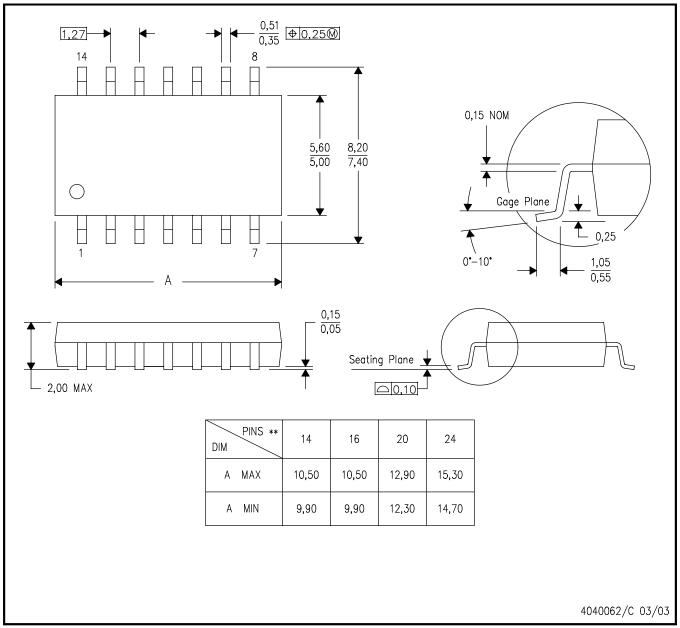
D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G**)

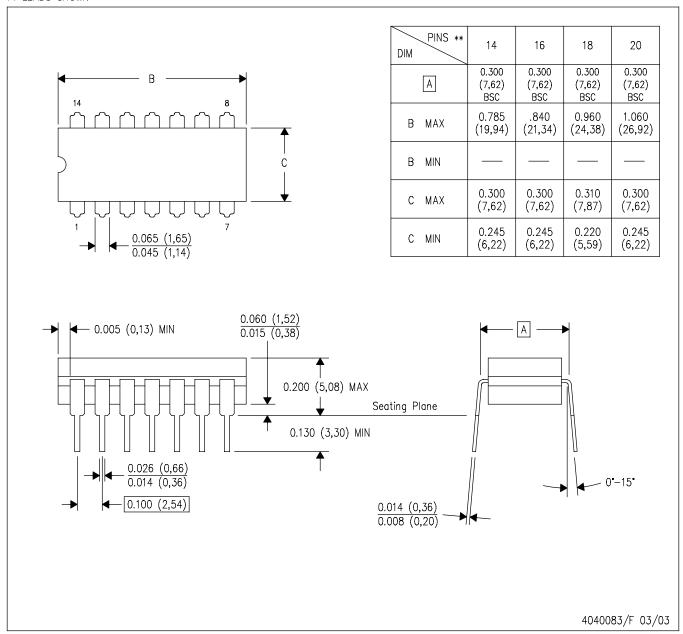
14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

14 LEADS SHOWN



NOTES:

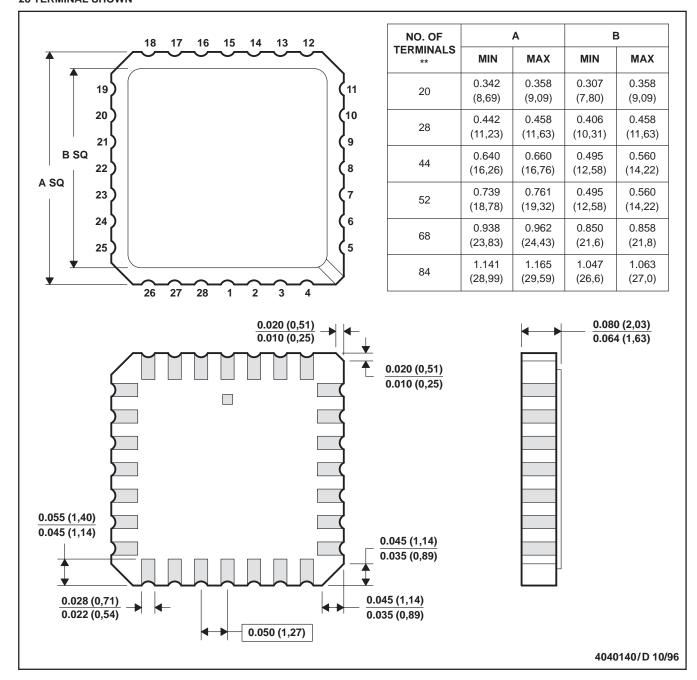
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



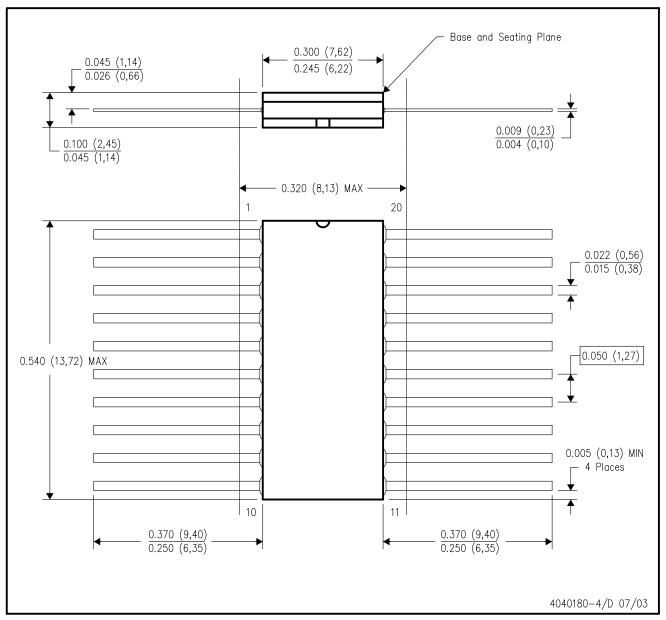
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



W (R-GDFP-F20)

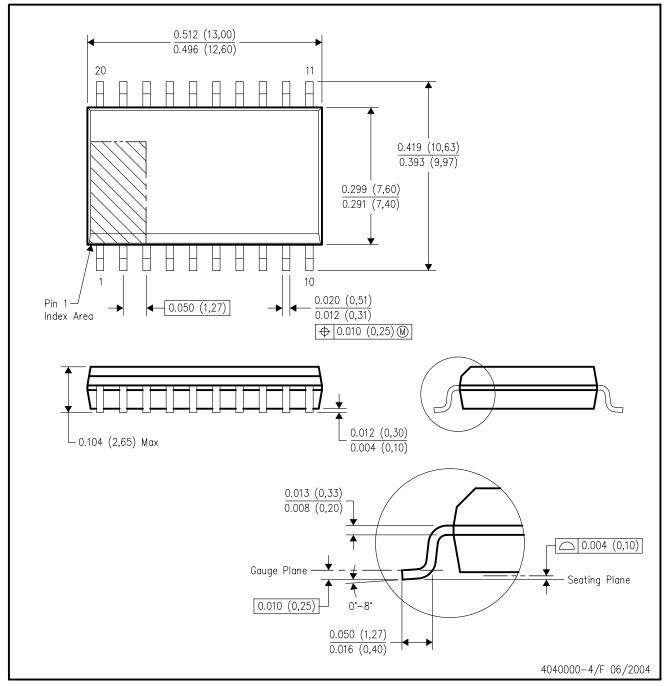
CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE

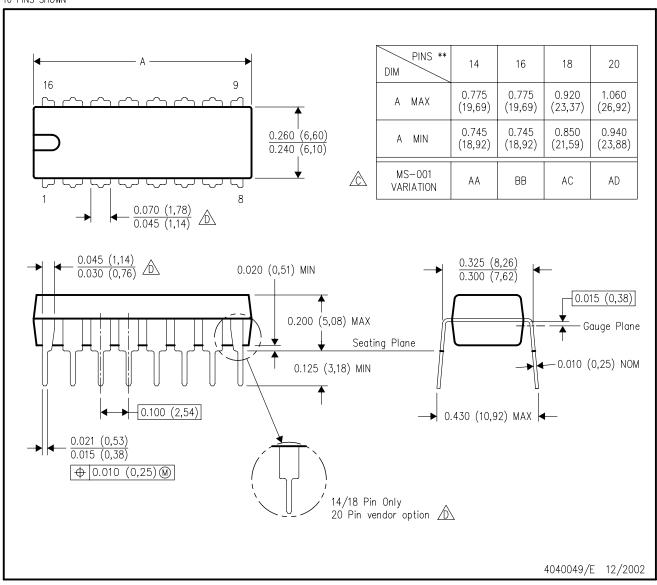


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

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